Product Change Notification: MFOL-29XUOF620

Date:

02-Feb-2026

Product Category:

CAN Controller

Notification Subject:

CCB 8015 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material, MC27 as a new mold compound material, and EP27 as a new die attach material for MCP2515T-I/STRB4, MCP2515T-E/STRB2, MCP2515-I/STRB2, MCP2515-E/STRB4, MCP2515T-E/ST, MCP2515-E/ST, MCP2515-E/STRB2, MCP2515T-I/STRB2, MCP2515T-I/ST, MCP2515-I/STRB4, MCP2515T-E/STRB4, MCP2515-I/ST, MCP2515-E/STVAO, MCP2515T-E/STVAO, MCP2515-I/STVAO, and MCP2515T-I/STVAO catalog part numbers (CPN) available in 20L TSSOP (4.4mm) packages at ANAP assembly site.

Affected CPNs:

MFOL-29XUOF620_Affected_CPN_02022026.pdf
MFOL-29XUOF620_Affected_CPN_02022026.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material, MC27 as a new mold compound material, and EP27 as a new die attach material for MCP2515T-I/STRB4, MCP2515T-E/STRB2, MCP2515-I/STRB2, MCP2515-E/STRB4, MCP2515T-E/ST, MCP2515-E/ST, MCP2515-E/STRB2, MCP2515T-I/STRB2, MCP2515T-I/ST, MCP2515-I/STRB4, MCP2515T-E/STRB4, MCP2515-I/ST, MCP2515-E/STVAO, MCP2515T-E/STVAO, MCP2515-I/STVAO, and MCP2515T-I/STVAO catalog part numbers (CPN) available in 20L TSSOP (4.4mm) packages at ANAP assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Amkor Technology Philippine (P1/P2), Inc. (ANAP)	Amkor Technology Philippine (P1/P2), Inc. (ANAP)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	8290 (PFAS)	EP27 (PFAS-Free)	Yes
Molding Compound Material	G700K	MC27	Yes
Lead-Frame Material	C194	C194	No
Lead-Frame DAP Surface Prep	Ring Ag (Bare Cu, Ag on lead)	Two-sided Roughened Ring Ag	Yes
Lead-Frame Design	See Pre and Post Change Summary attachment for comparison.		

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material, MC27 as a new mold compound material, and EP27 as a new die attach material standardize the use of PFAS free material at ANAP assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: October 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	February 2026				>	**October 2026**				
Work Week	06	07	08	09		40	41	42	43	44

Initial PCN Issue Date	X									
Qual Report Availability						X				
Final PCN Issue Date						X				

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: February 02, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-29XUOF620_Pre and Post Change Summary.pdf
PCN_MFOL-29XUOF620_Qualification Plan.pdf
PFAS Elimination and Die Attach_Explanation.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.